

SPECIFICATION FOR  
CONNECTOR USED FOR FPC/FFC WITH 1mm CONTACT SPACING  
SLW\_\_R/S-\_\_BLF

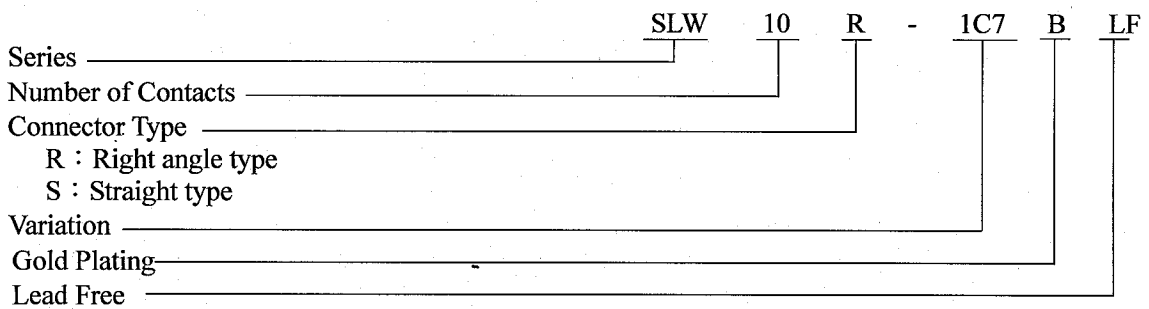
1. SCOPE

This specification covers the requirements for the connector (SLW\_\_R/S-\_\_) with 1mm spacing to which the edge of FPC (Flexible Printed Circuit) can be connected by Zero-Insertion-Force method.

2. APPLICABLE STANDARDS

JIS C 5402 Method for Test of Connectors for Electronic Equipment  
UL - 94 TESTS FOR FLAMMABILITY OF PLASTIC MATERIALS FOR PARTS IN DEVICES AND APPLIANCES.

3. CATALOG No. STRUCTURE



4. CONNECTOR SHAPE, DIMENSIONS

See attached drawings.

5. MATERIALS

See attached drawings.

6. ACCOMMODATED CONDUCTORS (FPC/)

See attached drawings.

7. ACCOMMODATED P.C.BOARD (P.C.B on which the connector is mounted)

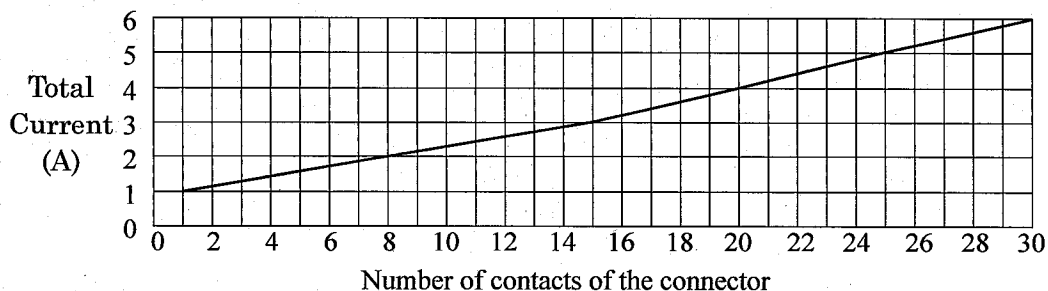
See attached drawings.

8. RATING

- 8-1. Voltage : A.C.100V      D.C.100V
- 8-2. Current : A.C.1A      D.C.1A (Refer to the following note.)
- 8-3. Operating Temperature : -55°C ~ +85°C  
(Including terminal temperature rises)

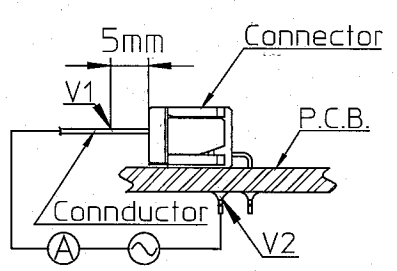
NOTE

Allowable maximum current for one contact is 1A. Total allowable current for a whole connector is the value which is shown in the following figure.



9. PERFORMANCE CHARACTERISTICS

9-1. Electrical Performance

No.	Test Item	Test Method	Requirements
9-1-1	Contact resistance	<p>1) Measure contact resistance between <math>V_1</math>-<math>V_2</math> by voltage drop method by the following circuit.</p>  <p>2) Open circuit voltage : Less than A.C.20mV 3) Test current : Less than A.C.20mA</p>	<p>1) Initial value : Less than 30mΩ 2) Contact resistance after the test is in accordance with the value specified in each test item.</p>
9-1-2	Insulation resistance	<p>1) Measure insulation resistance between adjacent contacts in a connector individual. 2) Test voltage : D.C.500V 3) Read value one minute after applying test voltage.</p>	<p>1) More than 500MΩ</p>
9-1-3	Dielectric withstanding voltage	<p>1) For one minute, apply A.C.500V between adjacent contacts in a connector individual. 2) Set current : A.C.1mA</p>	<p>1) Free from any short circuit and insulation breakdown.</p>

9-2. Mechanical Performance

No.	Test Item	Test Method	Requirements
9-2-1	Vibration (Sinusoidal)	<p>JIS C 0040 1) Frequency range : 10 ~ 500Hz 2) Amplitude : 0.75mm or Acceleration : 100mm<sup>2</sup> 3) Sweep rate : 1 octave/minute 4) Kind of test : Sweep endurance test 5) Test time : 10 cycles</p>	<p>1) During the test, no circuit opening for more than 1μs. 2) Free from any defect such as break, deformation, loosening and falling off etc. on each portion of the connector.</p>
9-2-2	Durability (Slider operation)	<p>1) Measure contact resistance before and after the test by the method in clause 9-1-1 by mating the accommodated conductor specified in clause 6. 2) Number of slider open and close : 20 times (Insert and extract the conductor for each opening of the slider.)</p>	<p>1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ 3) Free from any defect such as break etc. on the connector and the conductor.</p>

9-3. Climatic Category

No.	Test Item	Test Method	Requirements															
9-3-1	Damp heat (Steady state)	JIS C 0022 1) Measure contact resistance before and after the test by the method in clause 9-1-1 by using the accommodated conductor specified in clause 6. 2) Measure insulation resistance after the test by the method in clause 9-1-2. 3) Bath temperature : 40°C 4) Bath humidity : 90 ~ 95% (relative humidity) 5) Period of exposure : 48 hours 6) Expose conductor and connector after mating them and dry them naturally after posttreating. (Without insertion and separation)	1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ 3) Insulation resistance after the test : More than 100MΩ															
9-3-2	Salt spray	JIS C 0023 1) Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor specified in clause 6. 2) Salt solution concentration : 5% 3) Period of exposure : 48 hours 4) Expose conductor and connector in mated condition and dry them naturally posttreatment. (24 hours)	1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ															
9-3-3	Change of temperature	JIS C 0025 1) Measure contact resistance before and after the test according to the method in clause 9-1-1 by using accommodated conductor in clause 6. 2) One cycle of temperature is as follow and test 5 cycles. <table border="1" data-bbox="628 1503 1038 1675"> <thead> <tr> <th>Step</th> <th>Temp.(°C)</th> <th>Time(min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55±3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25±2</td> <td>2 ~ 3</td> </tr> <tr> <td>3</td> <td>85±2</td> <td>30</td> </tr> <tr> <td>4</td> <td>25±2</td> <td>2 ~ 3</td> </tr> </tbody> </table> 3) Expose conductor and connector by mating them and leave them under normal temperature.	Step	Temp.(°C)	Time(min.)	1	-55±3	30	2	25±2	2 ~ 3	3	85±2	30	4	25±2	2 ~ 3	1) Initial contact resistance : Less than 30mΩ 2) Contact resistance after the test : Less than 50mΩ 3) Free from any defect such as crack, warping and deformation etc. on each portion the connector.
Step	Temp.(°C)	Time(min.)																
1	-55±3	30																
2	25±2	2 ~ 3																
3	85±2	30																
4	25±2	2 ~ 3																

## 9-4. Other performance

No.	Test Item	Test Method	Requirements						
9-4-1	Soldering (Solderability)	JIS C 0050 Test Method : Ta 1) Test connector is soldered by dipping in inactive rosin family flux after mounted on P.C.Board. <table border="1"> <thead> <tr> <th>Soldering bath temp.(°C)</th> <th>Dipping time(s)</th> </tr> </thead> <tbody> <tr> <td>235±5</td> <td>5±0.5</td> </tr> </tbody> </table>	Soldering bath temp.(°C)	Dipping time(s)	235±5	5±0.5	1) Actual soldered area must be more than 90% of the dipped area intended to be soldered.		
Soldering bath temp.(°C)	Dipping time(s)								
235±5	5±0.5								
9-4-2	Soldering (Resistance to reflow soldering)	JIS C 0050 Test Method : Ta 1) Test connector is soldered by the following condition after mounted P.C.Board. <table border="1"> <thead> <tr> <th>Soldering bath temp.(°C)</th> <th>Dipping time(s)</th> </tr> </thead> <tbody> <tr> <td>350±10</td> <td>3.5±0.5</td> </tr> <tr> <td>260±5</td> <td>10.1±1</td> </tr> </tbody> </table>	Soldering bath temp.(°C)	Dipping time(s)	350±10	3.5±0.5	260±5	10.1±1	1) Free from any damage on concerning feature and contacting performance after soldered.
Soldering bath temp.(°C)	Dipping time(s)								
350±10	3.5±0.5								
260±5	10.1±1								

## 10. INDICATION AND PACKAGING

## 10-1. Indication

- 1) Catalog number and lot number are not indicated on the connector.
- 2) Catalog number and quantity shall be indicated on the surface on the package box.

## 10-2. Packaging

- 1) The connector individuals are put into the package box with specified quantity in accordance with the method specified in the separate packaging specification.

## 11. Remarks

11-1. Please use for Gold plating FPC as accommodated conductor.

11-2. In case of using this connector as multi-conductors, please mate by pushing slider center portion (Excepting conductor guide portion) by all means since sometimes slider center portion does not go down perfectly (Especially in case of combination with FFC of more than 21 conductors.)

11-3. Please refer to the "Handling procedures and remarks" before use.